

The book was found

Silicon Wafer Bonding Technology For VLSI And MEMS Applications (Emis Processing Series, 1)



Synopsis

The use of silicon-on-insulator (SOI) technology in microelectronics is proliferating and is ready to be applied in a growing number of IC fabrication situations. Bonding of single crystal Si to dielectrics, normally silicon dioxide, is a key method of producing SOI structures and this work is designed to assist engineers directly in applying emerging SOI technology in practice. Wafer bonding principles, grind and polish back, Smartcut, Eltran and wafer characterization are all explained and illustrated for the benefit of the process development engineer. Also available: Silicide Technology for Integrated Circuits - ISBN 9780863413520 Fabrication of GaAs Devices - ISBN 9780863413537

The Institution of Engineering and Technology is one of the world's leading professional societies for the engineering and technology community. The IET publishes more than 100 new titles every year; a rich mix of books, journals and magazines with a back catalogue of more than 350 books in 18 different subject areas including: -Power & Energy -Renewable Energy -Radar, Sonar & Navigation -Electromagnetics -Electrical Measurement -History of Technology -Technology Management

Book Information

Series: Emis Processing Series, 1 (Book 1)

Hardcover: 200 pages

Publisher: The Institution of Engineering and Technology (May 15, 2002)

Language: English

ISBN-10: 0852960395

ISBN-13: 978-0852960394

Product Dimensions: 0.8 x 7.5 x 10 inches

Shipping Weight: 1 pounds

Average Customer Review: Be the first to review this item

Best Sellers Rank: #2,464,084 in Books (See Top 100 in Books) #91 in Books > Engineering & Transportation > Engineering > Electrical & Electronics > Circuits > VLSI & ULSI #210 in Books > Engineering & Transportation > Engineering > Materials & Material Science > Extraction & Processing #401 in Books > Engineering & Transportation > Engineering > Electrical & Electronics > Electronics > Semiconductors

[Download to continue reading...](#)

Silicon Wafer Bonding Technology for VLSI and MEMS Applications (Emis Processing Series, 1)

Practical MEMS: Design of microsystems, accelerometers, gyroscopes, RF MEMS, optical MEMS,

and microfluidic systems Wafer Paper Cakes: Modern Cake Designs and Techniques for Wafer Paper Flowers and More BioNanoFluidic MEMS (MEMS Reference Shelf) Silicon Processing for the VLSI Era, Vol. 1: Process Technology Silicon Processing for the VLSI Era, Vol. 4: Deep-Submicron Process Technology Silicon Processing for the VLSI Era, Vol. 2: Process Integration Silicon Processing for the VLSI Era, Vol. 3: The Submicron MOSFET Silicon VLSI Technology: Fundamentals, Practice, and Modeling Silicon VLSI Technology VLSI Test Principles and Architectures: Design for Testability (The Morgan Kaufmann Series in Systems on Silicon) Circuits, Interconnections, and Packaging for VLSI (Addison-Wesley VLSI systems series) Mems for Biomedical Applications (Woodhead Publishing Series in Biomaterials) VLSI Fabrication Principles: Silicon and Gallium Arsenide, 2nd Edition VLSI DESIGN SIMPLE AND LUCID EXPLANATION: VLSI design for students CMOS VLSI Engineering: Silicon-on-Insulator (SOI) Thug Waffles: Waffle Recipes To Die For - Dangerously Delicious, Criminally Sweet & Savory Belgian Syrup Wafer Kitchen Cookbook VLSI Digital Signal Processing Systems: Design and Implementation VLSI Analog Signal Processing Circuits MEMS and Microsystems: Design, Manufacture, and Nanoscale Engineering

[Contact Us](#)

[DMCA](#)

[Privacy](#)

[FAQ & Help](#)